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Renesas Technology Corp.
Customer Support Dept.
April 1, 2003

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Keep safety first in your circuit designs!

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Remember to give due consideration to safety when making your circuit designs, with appropriate measures such as (i) placement of substitutive, auxiliary circuits, (ii) use of nonflammable material or (iii) prevention against any malfunction or mishap.

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HD74HC257

Quad. 2-to-1-line Data Selectors/Multiplexers (with noninverted 3-state outputs)



ADE-205-478 (Z)
1st. Edition
Sep. 2000

Description

The large output drive capability coupled with the 3-state feature make this device ideal for interfacing with bus lines in a bus organized system. When the output control input line is taken high, the outputs of all four multiplexers are sent into a high impedance state. When the output control line is low, the select input chooses whether the A or B input is used.

Features

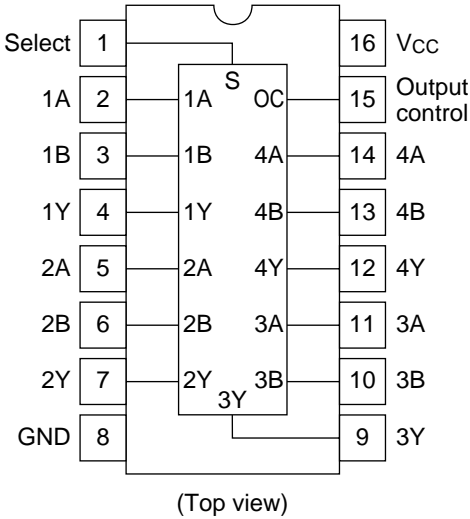
- High Speed Operation: t_{pd} (Data to Y) = 10.5 ns typ ($C_L = 50$ pF)
- High Output Current: Fanout of 15 LSTTL Loads
- Wide Operating Voltage: $V_{CC} = 2$ to 6 V
- Low Input Current: 1 μ A max
- Low Quiescent Supply Current: I_{CC} (static) = 4 μ A max ($T_a = 25^\circ\text{C}$)

Function Table

Inputs		Outputs		
Output Control	Select	A	B	Y
L	L	L	X	L
L	L	H	X	H
L	H	X	L	L
L	H	X	H	H
H	X	X	X	High impedance

Notes H: high level, L: low level, X: irrelevant

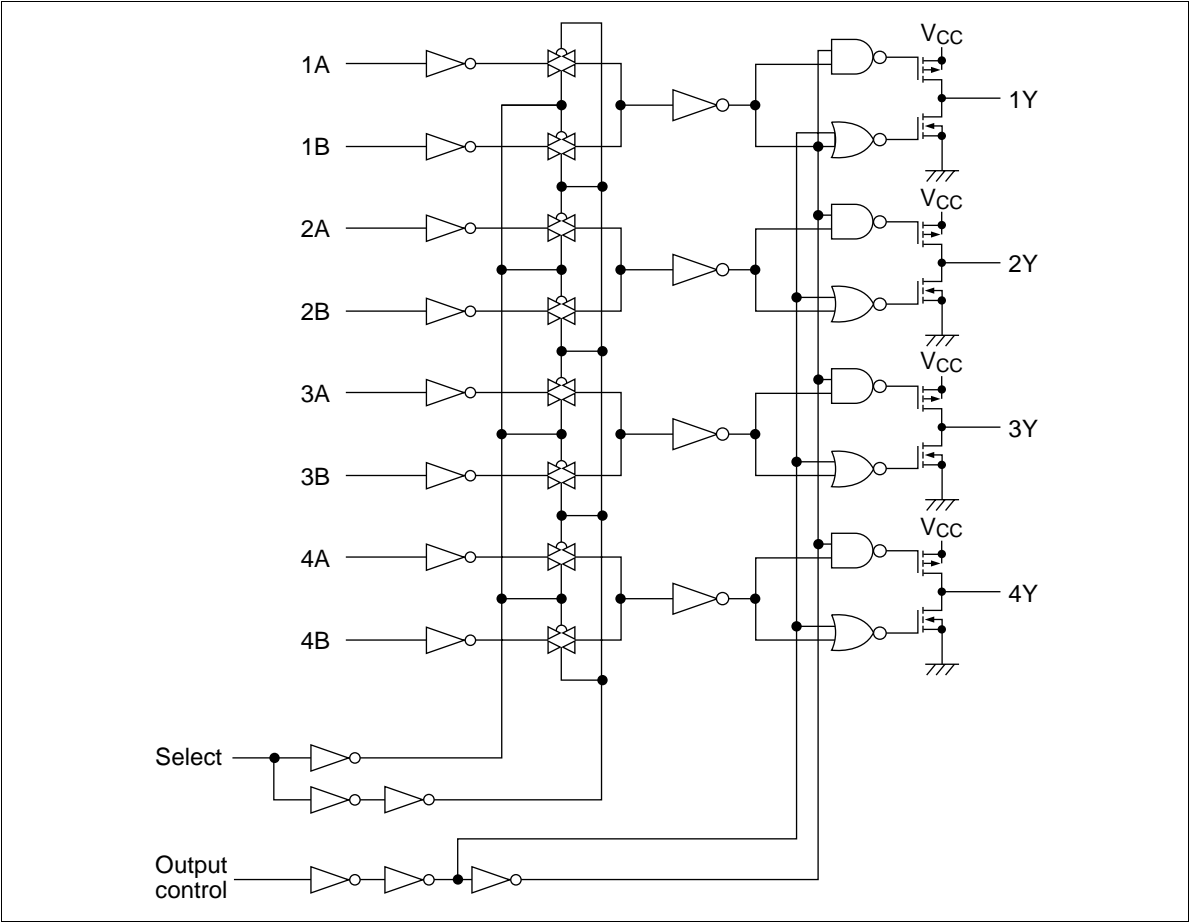
Pin Arrangement



Absolute Maximum Ratings

Item	Symbol	Rating	Unit
Supply voltage range	V_{CC}	-0.5 to +7.0	V
Input voltage	V_{IN}	-0.5 to $V_{CC} + 0.5$	V
Output voltage	V_{OUT}	-0.5 to $V_{CC} + 0.5$	V
DC current drain per pin	I_{OUT}	± 35	mA
DC current drain per V_{CC} , GND	I_{CC} , I_{GND}	± 75	mA
DC input diode current	I_{IK}	± 20	mA
DC output diode current	I_{OK}	± 20	mA
Power dissipation per package	P_T	500	mW
Storage temperature	T_{stg}	-65 to +150	°C

Logic Diagram



DC Characteristics

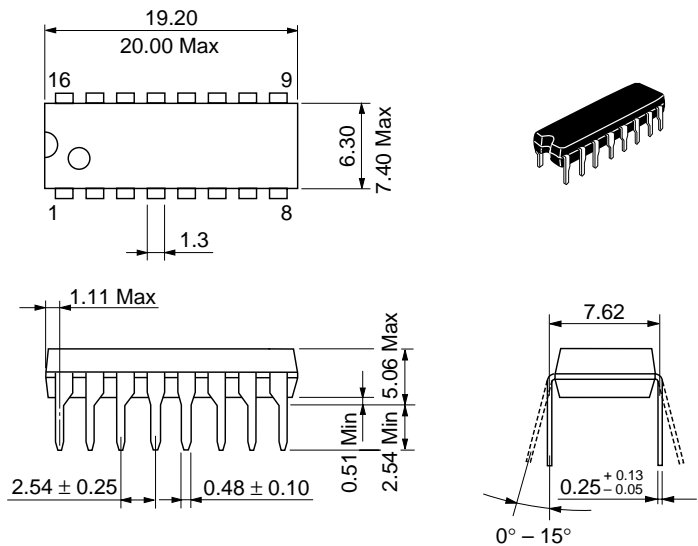
Item	Symbol	V _{CC} (V)	Ta = 25°C			Ta = -40 to +85°C		Unit	Test Conditions
			Min	Typ	Max	Min	Max		
Input voltage	V _{IH}	2.0	1.5	—	—	1.5	—	V	
		4.5	3.15	—	—	3.15	—		
		6.0	4.2	—	—	4.2	—		
	V _{IL}	2.0	—	—	0.5	—	0.5	V	
		4.5	—	—	1.35	—	1.35		
		6.0	—	—	1.8	—	1.8		
Output voltage	V _{OH}	2.0	1.9	2.0	—	1.9	—	V	Vin = V _{IH} or V _{IL} I _{OH} = -20 μA
		4.5	4.4	4.5	—	4.4	—		
		6.0	5.9	6.0	—	5.9	—		
		4.5	4.18	—	—	4.13	—		
		6.0	5.68	—	—	5.63	—		
	V _{OL}	2.0	—	0.0	0.1	—	0.1	V	Vin = V _{IH} or V _{IL} I _{OL} = 20 μA
		4.5	—	0.0	0.1	—	0.1		
		6.0	—	0.0	0.1	—	0.1		
		4.5	—	—	0.26	—	0.33		
		6.0	—	—	0.26	—	0.33		
Off-state output current	I _{OZ}	6.0	—	—	±0.5	—	±5.0	μA	Vin = V _{IH} or V _{IL} , Vout = V _{CC} or GND
Input current	I _{in}	6.0	—	—	±0.1	—	±1.0	μA	Vin = V _{CC} or GND
Quiescent supply current	I _{CC}	6.0	—	—	4.0	—	40	μA	Vin = V _{CC} or GND, Iout = 0 μA

AC Characteristics ($C_L = 50$ pF, Input $t_r = t_f = 6$ ns)

Item	Symbol	V _{CC} (V)	Ta = 25°C			Ta = −40 to +85°C		Unit	Test Conditions
			Min	Typ	Max	Min	Max		
Propagation delay time	t _{PHL}	2.0	—	—	115	—	145	ns	Data to Y
		4.5	—	11	23	—	29		
		6.0	—	—	20	—	25		
	t _{PLH}	2.0	—	—	115	—	145	ns	
		4.5	—	10	23	—	29		
		6.0	—	—	20	—	25		
	t _{PHL}	2.0	—	—	115	—	145	ns	Select to Y
		4.5	—	14	23	—	29		
		6.0	—	—	20	—	25		
	t _{PLH}	2.0	—	—	115	—	145	ns	
		4.5	—	14	23	—	29		
		6.0	—	—	20	—	25		
Output enable time	t _{ZL}	2.0	—	—	150	—	190	ns	Output control to Y
		4.5	—	11	30	—	38		
		6.0	—	—	26	—	33		
	t _{ZH}	2.0	—	—	150	—	190	ns	
		4.5	—	13	30	—	38		
		6.0	—	—	26	—	33		
Output disable time	t _{LZ}	2.0	—	—	150	—	190	ns	Output control to Y
		4.5	—	14	30	—	38		
		6.0	—	—	26	—	33		
	t _{HZ}	2.0	—	—	150	—	190	ns	
		4.5	—	18	30	—	38		
		6.0	—	—	26	—	33		
Output rise/fall time	t _{TLH}	2.0	—	—	60	—	75	ns	
	t _{THL}	4.5	—	4	12	—	15		
		6.0	—	—	10	—	13		
Input capacitance	C _{in}	—	—	5	10	—	10	pF	

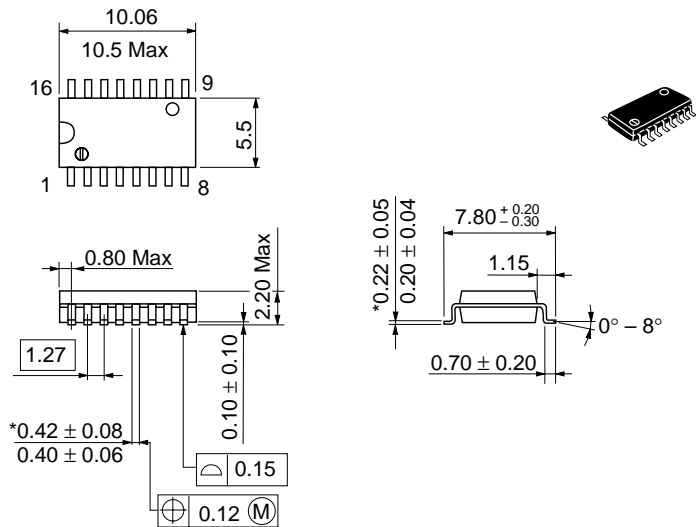
Package Dimensions

Unit: mm



Hitachi Code	DP-16
JEDEC	Conforms
EIAJ	Conforms
Mass (reference value)	1.07 g

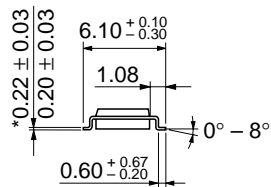
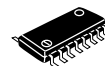
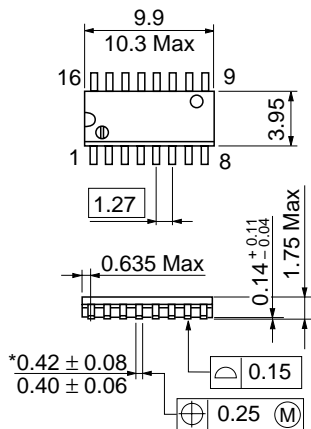
Unit: mm



*Dimension including the plating thickness
Base material dimension

Hitachi Code	FP-16DA
JEDEC	—
EIAJ	Conforms
Mass (reference value)	0.24 g

Unit: mm



*Dimension including the plating thickness
Base material dimension

Hitachi Code	FP-16DN
JEDEC	Conforms
EIAJ	Conforms
Mass (reference value)	0.15 g

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